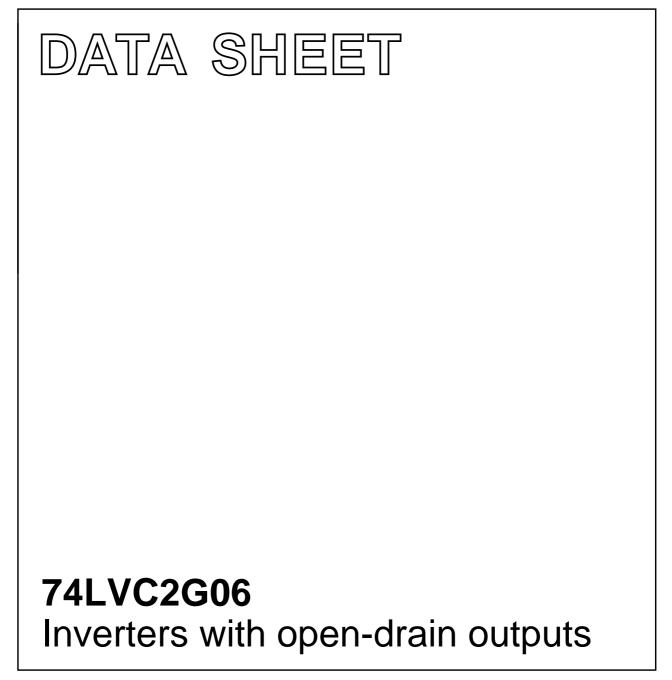
INTEGRATED CIRCUITS



Product specification

2003 Aug 25



### 74LVC2G06

### FEATURES

- Wide supply voltage range from 1.65 to 5.5 V
- 5 V tolerant input/output for interfacing with 5 V logic
- High noise immunity
- Complies with JEDEC standard:
  - JESD8-7 (1.65 to 1.95 V)
  - JESD8-5 (2.3 to 2.7 V)
  - JESD8B/JESD36 (2.7 to 3.6 V).
- –24 mA output drive (V<sub>CC</sub> = 3.0 V)
- CMOS low power consumption
- Latch-up performance exceeds 250 mA
- Direct interface with TTL levels
- Inputs accept voltages up to 5 V
- SOT363 and SOT457 package

**QUICK REFERENCE DATA** GND = 0 V;  $T_{amb} = 25 \degree C$ .

- ESD protection:
  - HBM EIA/JESD22-A114-A exceeds 2000 V
  - MM EIA/JESD22-A115-A exceeds 200 V.
- Specified from -40 to +85 °C and -40 to +125 °C.

### DESCRIPTION

The 74LVC2G06 is a high-performance, low-power, low-voltage, Si-gate CMOS device and superior to most advanced CMOS compatible TTL families.

Inputs can be driven from either 3.3 or 5 V devices. This feature allows the use of this device in a mixed 3.3 and 5 V environment.

Schmitt trigger action at all inputs makes the circuit tolerant for slower input rise and fall time.

This device is fully specified for partial power-down applications using  $I_{off}$ . The  $I_{off}$  circuitry disables the output, preventing the damaging backflow current through the device when it is powered down.

The 74LVC2G06 provides two inverting buffers.

The output of this device is an open drain and can be connected to other open-drain outputs to implement active-LOW wired-OR or active-HIGH wired-AND functions.

SYMBOL	PARAMETER	CONDITIONS	TYPICAL	UNIT
t <sub>PLZ</sub> /t <sub>PZL</sub>	propagation delay input nA to output nY	$V_{CC}$ = 1.8 V; $C_L$ = 30 pF; $R_L$ = 1 k $\Omega$	3.2	ns
		$V_{CC} = 2.5 \text{ V}; \text{ C}_{L} = 30 \text{ pF}; \text{ R}_{L} = 500 \Omega$	2.0	ns
		$V_{CC}$ = 2.7 V; $C_{L}$ = 50 pF; $R_{L}$ = 500 $\Omega$	2.6	ns
		$V_{CC} = 3.3 \text{ V}; \text{ C}_{L} = 50 \text{ pF}; \text{ R}_{L} = 500 \Omega$	2.3	ns
		$V_{CC} = 5.0 \text{ V}; \text{ C}_{L} = 50 \text{ pF}; \text{ R}_{L} = 500 \Omega$	1.6	ns
Cl	input capacitance		2.5	pF
C <sub>PD</sub>	power dissipation capacitance per gate	V <sub>CC</sub> = 3.3 V; notes 1 and 2	5.9	pF

#### Notes

1.  $C_{PD}$  is used to determine the dynamic power dissipation ( $P_D$  in  $\mu W$ ).

 $P_D = C_{PD} \times V_{CC}^2 \times f_i \times N + \sum (C_L \times V_{CC}^2 \times f_o)$  where:

 $f_i$  = input frequency in MHz;

 $f_o = output frequency in MHz;$ 

 $C_L$  = output load capacitance in pF;

V<sub>CC</sub> = supply voltage in Volts;

N = total load switching outputs;

 $\Sigma(C_L \times V_{CC}{}^2 \times f_o)$  = sum of the outputs.

2. The condition is  $V_I = GND$  to  $V_{CC}$ .

## 74LVC2G06

### FUNCTION TABLE

See note 1.

INPUT	OUTPUT
nA	nY
L	Z
Н	L

#### Note

- 1. H = HIGH voltage level;
  - L = LOW voltage level;
  - Z = high-impedance OFF-state.

### **ORDERING INFORMATION**

TYPE NUMBER	PACKAGE							
	TEMPERATURE RANGE	PINS	PACKAGE	MATERIAL	CODE	MARKING		
74LVC2G06GW	–40 to +125 °C	6	SC-88	plastic	SOT363	V6		
74LVC2G06GV	–40 to +125 °C	6	SC-74	plastic	SOT457	V06		

Γ

### PINNING

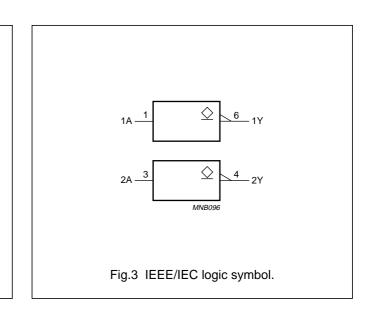
PIN	SYMBOL	DESCRIPTION
1	1A	data input
2	GND	ground (0 V)
3	2A	data input
4	2Y	data output
5	V <sub>CC</sub>	supply voltage
6	1Y	data output

6

2Y

MNB095

Fig.2 Logic symbol.



### 74LVC2G06

### **RECOMMENDED OPERATING CONDITIONS**

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V <sub>CC</sub>	supply voltage		1.65	5.5	V
VI	input voltage		0	5.5	V
Vo	output voltage	active mode	0	V <sub>CC</sub>	V
		V <sub>CC</sub> = 0 V; Power-down mode	0	5.5	V
T <sub>amb</sub>	operating ambient temperature		-40	+125	°C
t <sub>r</sub> , t <sub>f</sub>	input rise and fall times	$V_{CC} = 1.65$ to 2.7 V	0	20	ns/V
		$V_{CC} = 2.7$ to 5.5 V	0	10	ns/V

### LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134); voltages are referenced to GND (ground = 0 V).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V <sub>CC</sub>	supply voltage		-0.5	+6.5	V
I <sub>IK</sub>	input diode current	V <sub>1</sub> < 0	_	-50	mA
VI	input voltage	note 1	-0.5	+6.5	V
I <sub>OK</sub>	output diode current	V <sub>O</sub> < 0	-	-50	mA
Vo	output voltage	active mode; notes 1 and 2	-0.5	V <sub>CC</sub> + 0.5	V
		Power-down mode; notes 1 and 2	-0.5	+6.5	V
lo	output source or sink current	V <sub>O</sub> = 0 to 6.5 V	_	50	mA
I <sub>CC</sub> , I <sub>GND</sub>	V <sub>CC</sub> or GND current		_	±100	mA
T <sub>stg</sub>	storage temperature		-65	+150	°C
PD	power dissipation	T <sub>amb</sub> = -40 to +125 °C	_	300	mW

#### Notes

- 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
- 2. When  $V_{CC} = 0 V$  (Power-down mode), the output voltage can be 5.5 V in normal operation.

## 74LVC2G06

### DC CHARACTERISTICS

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

		TEST COND	TEST CONDITIONS		TVD			
SYMBOL	PARAMETER	OTHER	V <sub>CC</sub> (V)	MIN.	TYP.	MAX.		
T <sub>amb</sub> = -40	<b>) to +85</b> ° <b>C</b> ; note 1				•		•	
V <sub>IH</sub>	HIGH-level input voltage		1.65 to 1.95	$0.65 \times V_{CC}$	-	-	V	
			2.3 to 2.7	1.7	-	-	V	
			2.7 to 3.6	2.0	_	-	V	
			4.5 to 5.5	$0.7 \times V_{CC}$	-	-	V	
V <sub>IL</sub>	LOW-level input voltage		1.65 to 1.95	_	-	$0.35 \times V_{CC}$	V	
			2.3 to 2.7	_	_	0.7	V	
			2.7 to 3.6	-	-	0.8	V	
			4.5 to 5.5	_	_	$0.3  imes V_{CC}$	V	
V <sub>OL</sub>	LOW-level output voltage	$V_{I} = V_{IH} \text{ or } V_{IL}$						
		I <sub>O</sub> = 100 μA	1.65 to 5.5	_	-	0.1	V	
		l <sub>O</sub> = 4 mA	1.65	_	-	0.45	V	
		I <sub>O</sub> = 8 mA	2.3	_	-	0.3	V	
		l <sub>O</sub> = 12 mA	2.7	_	-	0.4	V	
		I <sub>O</sub> = 24 mA	3.0	_	-	0.55	V	
		I <sub>O</sub> = 32 mA	4.5	_	-	0.55	V	
ILI	input leakage current	$V_{I} = 5.5 V \text{ or GND}$	1.65 to 5.5	-	±0.1	±5	μA	
I <sub>OZ</sub>	3-state output OFF-state current	$V_{I} = V_{IH} \text{ or } V_{IL};$ $V_{O} = V_{CC} \text{ or } GND$	5.5	-	±0.1	±10	μA	
l <sub>off</sub>	power OFF leakage current	$V_{\rm I}$ or $V_{\rm O}$ = 5.5 V	0	-	±0.1	±10	μA	
I <sub>CC</sub>	quiescent supply current	$V_{I} = V_{CC}$ or GND; $I_{O} = 0$	5.5	-	0.1	10	μA	
$\Delta I_{CC}$	additional quiescent supply current per pin	$V_{I} = V_{CC} - 0.6 \text{ V};$ $I_{O} = 0$	2.3 to 5.5	-	5	500	μA	

## 74LVC2G06

	DADAMETED	TEST COND	ITIONS					
SYMBOL	PARAMETER	OTHER	V <sub>CC</sub> (V)	- MIN.	TYP.	MAX.		
T <sub>amb</sub> = -40	) to +125 °C							
VIH	HIGH-level input voltage		1.65 to 1.95	$0.65 \times V_{CC}$	-	-	V	
			2.3 to 2.7	1.7	-	-	V	
			2.7 to 3.6	2.0	-	-	V	
			4.5 to 5.5	$0.7 \times V_{CC}$	_	-	V	
V <sub>IL</sub>	LOW-level input voltage		1.65 to 1.95	_	_	$0.35 \times V_{CC}$	V	
			2.3 to 2.7	_	-	0.7	V	
			2.7 to 3.6	_	_	0.8	V	
			4.5 to 5.5	_	-	$0.3 \times V_{CC}$	V	
V <sub>OL</sub>	LOW-level output voltage	$V_{I} = V_{IH} \text{ or } V_{IL}$						
		I <sub>O</sub> = 100 μA	1.65 to 5.5	_	_	0.1	V	
		I <sub>O</sub> = 4 mA	1.65	_	_	0.70	V	
		I <sub>O</sub> = 8 mA	2.3	_	_	0.45	V	
		I <sub>O</sub> = 12 mA	2.7	_	_	0.60	V	
		I <sub>O</sub> = 24 mA	3.0	_	-	0.80	V	
		I <sub>O</sub> = 32 mA	4.5	_	-	0.80	V	
ILI	input leakage current	$V_{I} = 5.5 V \text{ or GND}$	1.65 to 5.5	_	_	±20	μA	
I <sub>OZ</sub>	3-state output OFF-state current	$V_{I} = V_{IH} \text{ or } V_{IL};$ $V_{O} = V_{CC} \text{ or } GND$	5.5	-	-	±10	μA	
l <sub>off</sub>	power OFF leakage current	$V_{\rm I}$ or $V_{\rm O}$ = 5.5 V	0	-	-	±20	μA	
I <sub>CC</sub>	quiescent supply current	$V_{I} = V_{CC}$ or GND; $I_{O} = 0$	5.5	-	-	40	μA	
$\Delta I_{CC}$	additional quiescent supply current per pin	$V_{I} = V_{CC} - 0.6 \text{ V};$ $I_{O} = 0$	2.3 to 5.5	-	-	5000	μA	

### Note

1. All typical values are measured at V\_{CC} = 3.3 V and T\_{amb} = 25 °C.

## 74LVC2G06

### AC CHARACTERISTICS

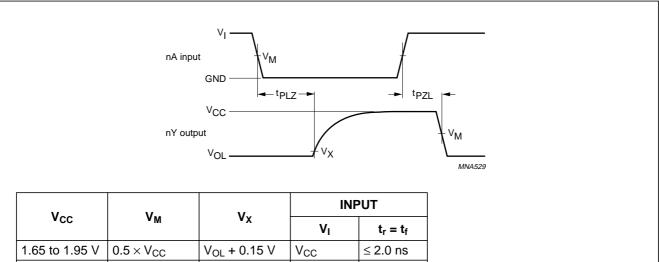
GND = 0 V.

		TEST CON	DITIONS	MAIN	TVD		
SYMBOL	PARAMETER	WAVEFORMS	V <sub>CC</sub> (V)	– MIN.	TYP.	MAX.	UNIT
T <sub>amb</sub> = -40	<b>) to +85</b> ° <b>C</b> ; note 1			•			
t <sub>PLZ</sub> /t <sub>PZL</sub>	propagation delay input nA to	see Figs 4 and 5	1.65 to 1.95	1.0	3.2	6.5	ns
	output nY		2.3 to 2.7	0.5	2.0	3.9	ns
			2.7	1.0	2.6	4.2	ns
			3.0 to 3.6	0.5	2.3	3.4	ns
			4.5 to 5.5	0.5	1.6	2.9	ns
T <sub>amb</sub> = -40	) to +125 °C						
t <sub>PLZ</sub> /t <sub>PZL</sub>	propagation delay input nA to	see Figs 4 and 5	1.65 to 1.95	1.0	-	8.2	ns
	output nY		2.3 to 2.7	0.5	-	4.9	ns
			2.7	1.0	-	5.3	ns
			3.0 to 3.6	0.5	-	4.3	ns
			4.5 to 5.5	0.5	-	3.7	ns

#### Note

1. All typical values are measured at  $T_{amb}$  = 25 °C and at  $V_{CC}$  = 1.8, 2.5, 2.7, 3.3 and 5.0 V respectively.

### AC WAVEFORMS

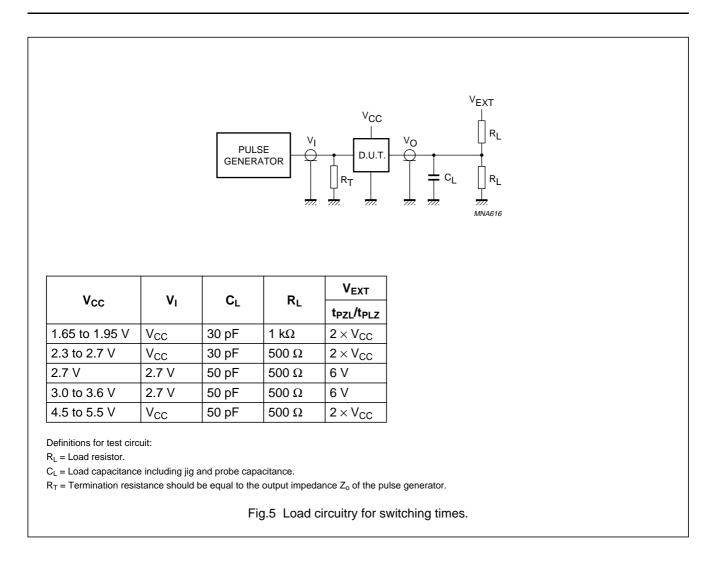


1.65 to 1.95 V	$0.5  imes V_{CC}$	V <sub>OL</sub> + 0.15 V	V <sub>CC</sub>	≤ 2.0 ns
2.3 to 2.7 V	$0.5 \times V_{CC}$	V <sub>OL</sub> + 0.15 V	V <sub>CC</sub>	≤ 2.0 ns
2.7 V	1.5 V	V <sub>OL</sub> + 0.3 V	2.7 V	≤ 2.5 ns
3.0 to 3.6 V	1.5 V	V <sub>OL</sub> + 0.3 V	2.7 V	≤ 2.5 ns
4.5 to 5.5 V	$0.5 \times V_{CC}$	V <sub>OL</sub> + 0.3 V	V <sub>CC</sub>	≤ 2.5 ns

 $V_{\text{OL}}$  and  $V_{\text{OH}}$  are typical output voltage drop that occur with the output load.

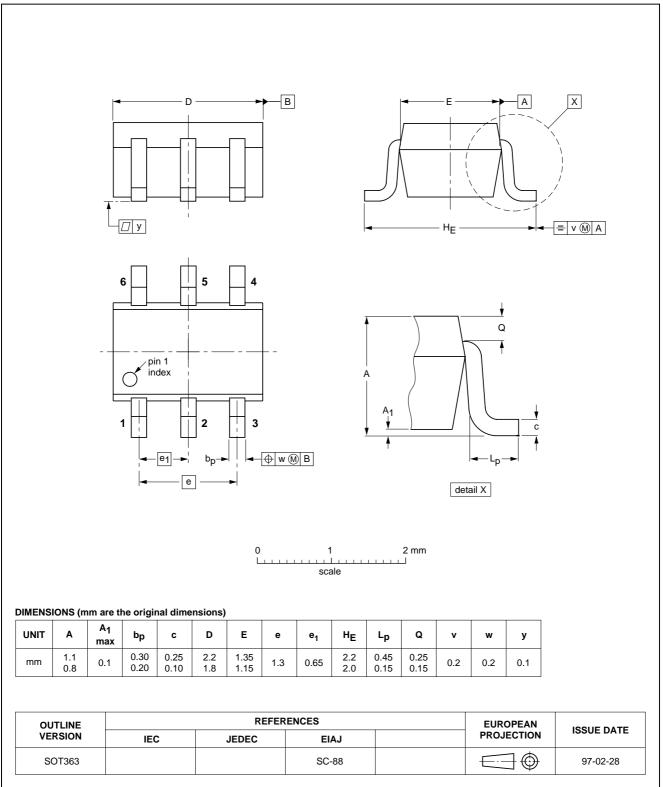
Fig.4 The input (nA) to output (nY) propagation delays.

## 74LVC2G06



### PACKAGE OUTLINES

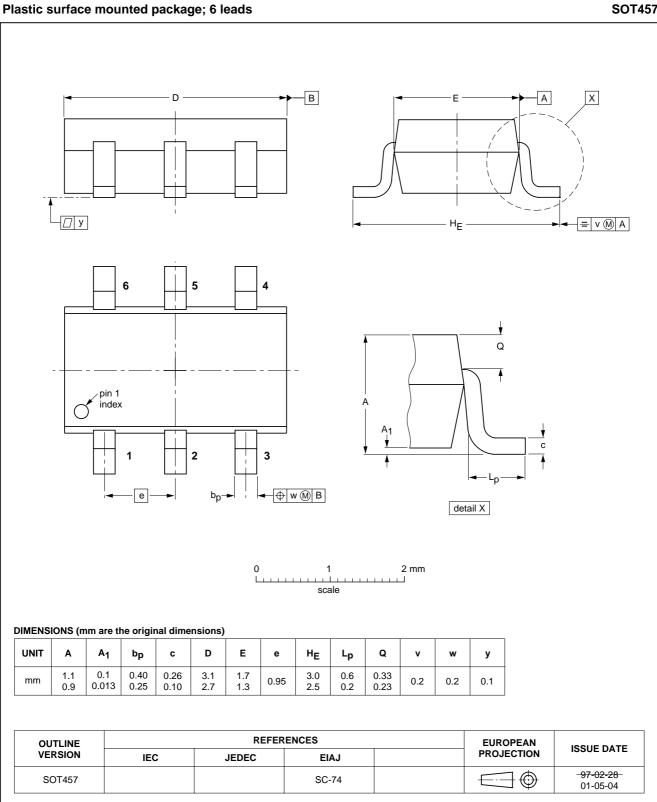
### Plastic surface mounted package; 6 leads



SOT363

### 74LVC2G06

### 74LVC2G06



SOT457

74LVC2G06

### DATA SHEET STATUS

LEVEL	DATA SHEET STATUS <sup>(1)</sup>	PRODUCT STATUS <sup>(2)(3)</sup>	DEFINITION
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